

ALUMINUM AND ALUMINUM ALLOY RADIATOR FOR SEMICONDUCTOR DEVICE
AND PROCESS FOR PRODUCING THE SAME

Abstract

An aluminum or aluminum alloy radiator possessing high reliability and excellent heat dissipation is provided.

5 A process for producing an aluminum alloy radiator is also provided which has improved adhesion between the radiator and the mold resin and can prevent cracking in a resin molded portion.

10 The aluminum alloy radiator, for a plastic molded type semiconductor device, comprising an anodized aluminum-iron alloy having an iron content of 0.5 to 3.0% by weight or an anodized aluminum-silicon alloy having a silicon content of 0.5 to 3.5% by weight. The process for producing an
15 aluminum alloy radiator for a plastic molded type semiconductor device, comprising the steps of: anodizing an aluminum alloy; and subjecting the anodized aluminum alloy to sealing, wherein the aluminum alloy radiator after the sealing is heat-treated at a temperature of 180 to 250°C.

20 (Fig. 1)

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